



Material Content Data Sheet



Sales Product Name				ESD208-B1-02EL E6327		Issued		19. July 2018	
MA#				MA001140030					
Package				PG-TSLP-2-19		Weight*		0.60 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.000	0.06		587		
	noble metal	gold	7440-57-5	0.001	0.23		2272		
	inorganic material	silicon	7440-21-3	0.010	1.68	1.97	16842	19701	
leadframe	non noble metal	nickel	7440-02-0	0.241	40.43	40.43	404319	404319	
wire	non noble metal	copper	7440-50-8	0.003	0.43	0.43	4341	4341	
encapsulation	organic material	carbon black	1333-86-4	0.002	0.28		2770		
	plastics	epoxy resin	-	0.048	8.03		80323		
	inorganic material	silicondioxide	60676-86-0	0.280	47.09	55.40	470860	553953	
leadfinish	noble metal	gold	7440-57-5	0.010	1.75	1.75	17508	17508	
plating	noble metal	palladium	7440-05-3	0.000	0.01		69		
	noble metal	gold	7440-57-5	0.000	0.01	0.02	109	178	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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